

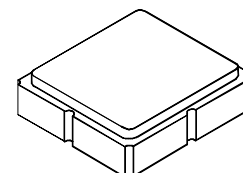
- **Low-loss UHF SAW Filter**
- **3.0 x 3.0 mm Surface-mount Package**

Maximum Rating

Rating	Value	Units
DC Voltage on any Non-ground Terminal	3	V
Operable Temperature Range	-45 to +125	°C
Specification Temperature Range	0 to +50	°C
Storage Temperature Range	-40 to +85	°C
Moisture Sensitivity Level	1	MSL

SF2471E

**915 MHz
SAW Filter**

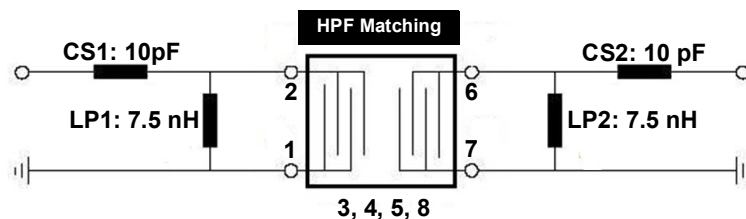


SM3030-8

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_C			915		MHz
Maximum Insertion Loss, 824 to 894 MHz	IL_{MAX}			1.8	2.5	dB
1850 to 1990 MHz				2.7	3.1	
Attenuation, 0 dB Reference:						dB
902.0 to 908.5 MHz (0 to +25°C)			1.0	4.0		
(+25 to +50°C)			1.5	4.0		
908.5 to 910.5 MHz			14	30		
910.5 to 920.5 MHz			14	19		
920.5 to 928.5 MHz			1.5	3.0		
Temperature Coefficient of Frequency				-36		ppm/k
Source Impedance Z_S				50		ohm
Load Impedance Z_L				50		

Case Style	SM3030-8 3.0 x 3.0 mm Nominal Footprint
Lid Symbolization, Y=year, WW=week, S=shift, dot=pin 1 indicator	B6, YWWS
Standard Reel Quantity	500 Pieces/Reel
Reel Size 7 inch	
Reel Size 13 inch	3000 Pieces/Reel

Electrical Connections	
Input	2
Output	6
All Others	1, 3, 4, 5, 7, 8



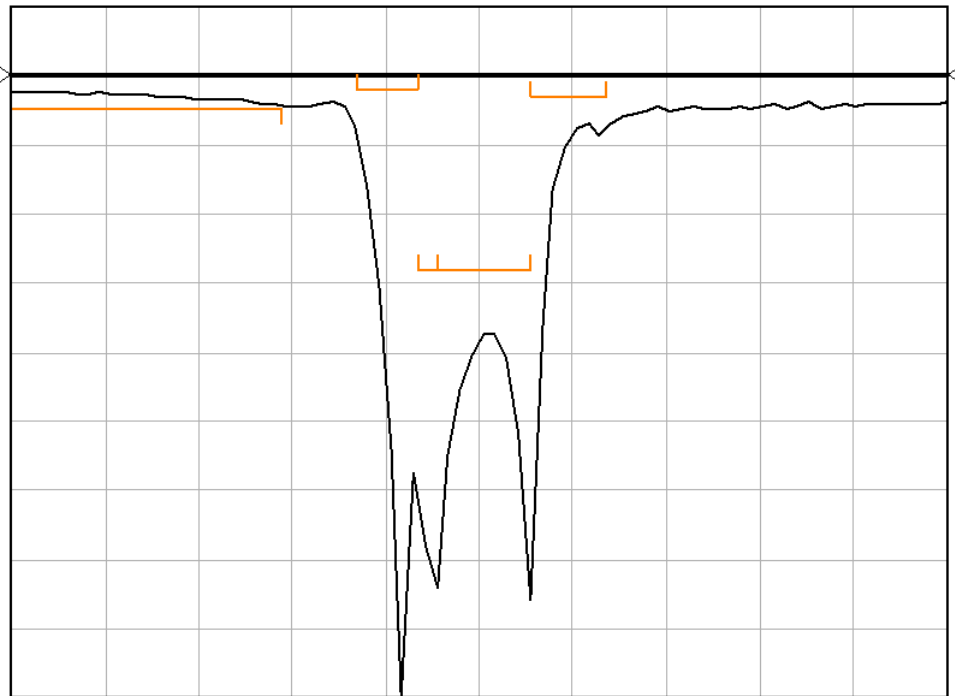
NOTES:

1. US and international patents may apply.
2. Murata, stylized Murata logo, and Murata N.A., Inc. are registered trademarks of Murata Manufacturing Co., Ltd.
3. Electrostatic Sensitive Device. Observe precautions for handling.

Transfer Function

Span: 100 MHz

S21 5dB/div



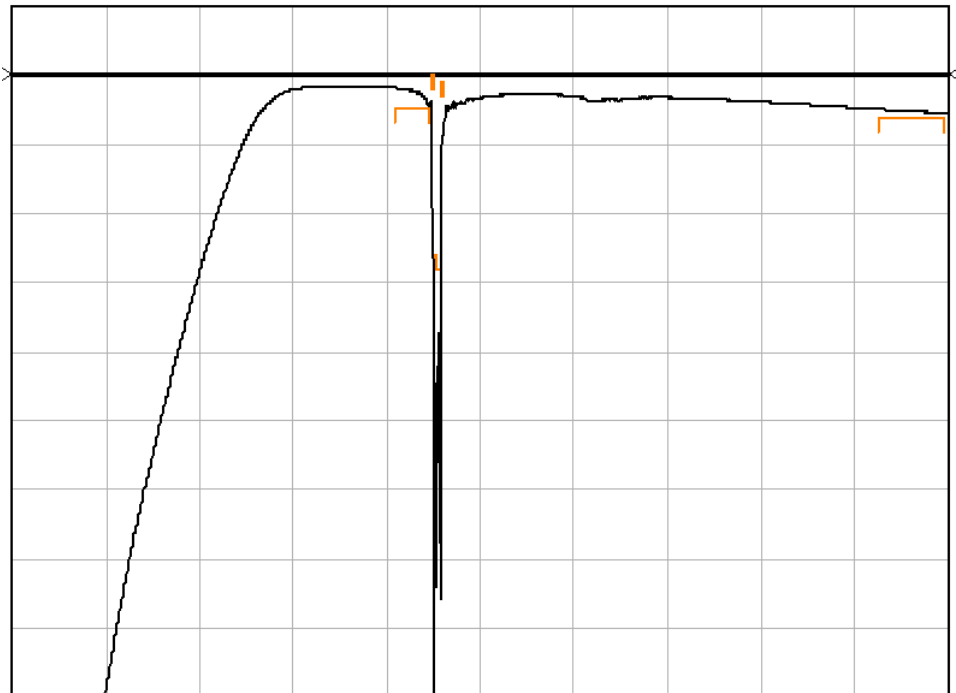
START 865.00 MHz

STOP 965.00 MHz

2019/03/01

Span: 2000 MHz

S21 5dB/div



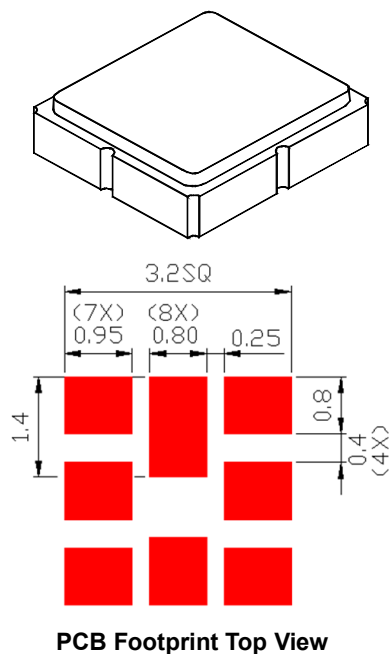
START 10.00 MHz

STOP 2000.00 MHz

2019/03/01

8-Terminal Ceramic Surface-Mount Case

3.0 x 3.0 mm Nominal Footprint



Case and PCB Footprint Dimensions

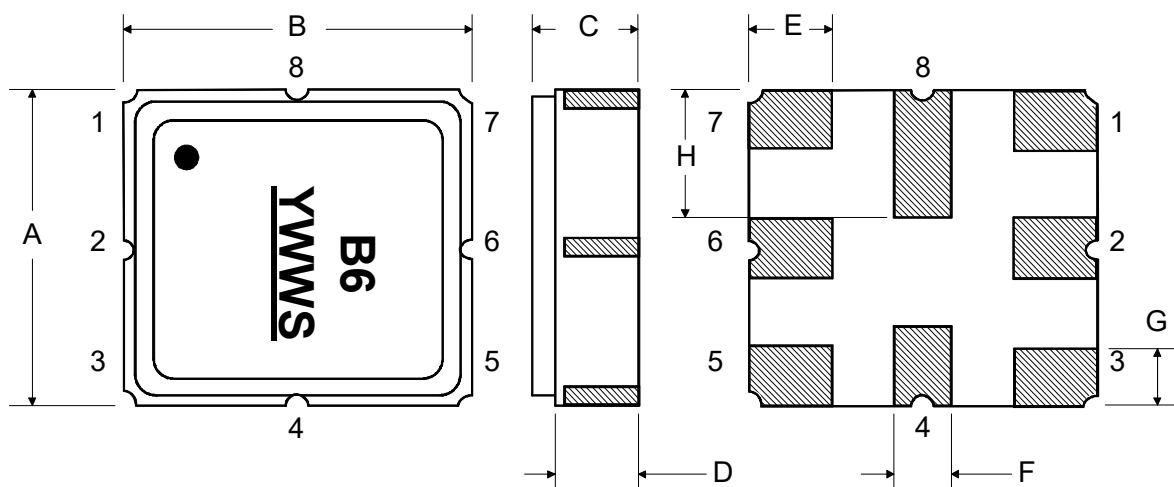
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.90	3.00	3.10	0.114	0.118	0.122
B	2.90	3.00	3.10	0.114	0.118	0.122
C	0.90	1.00	1.10	0.035	0.039	0.043
D	0.79	0.92	1.05	0.031	0.036	0.041
E	0.62	0.75	0.88	0.024	0.029	0.034
F	0.47	0.60	0.73	0.018	0.023	0.028
G	0.50	0.60	0.70	0.019	0.023	0.027
H	1.10	1.20	1.30	0.043	0.047	0.051

Case Materials

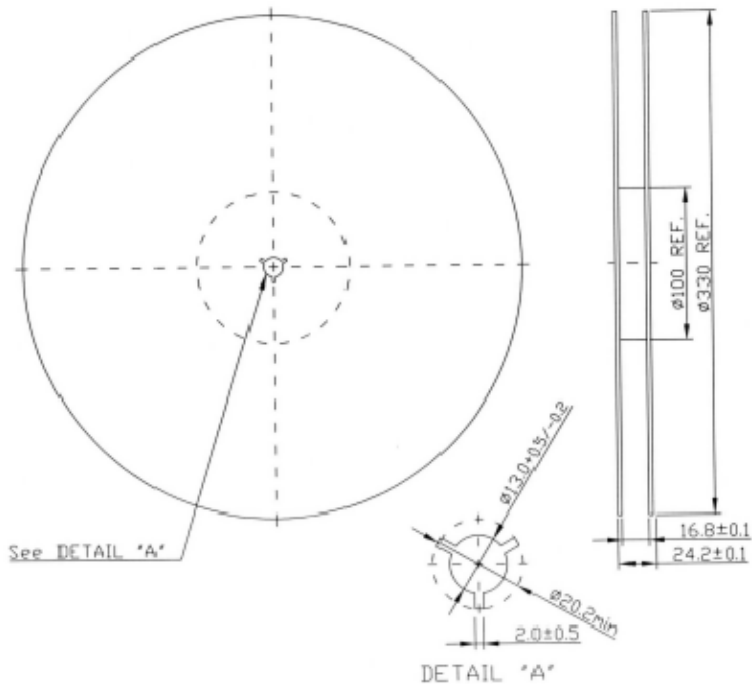
Materials	
Solder Pad Plating	0.3 to 1.0 µm Gold over 1.27 to 8.89 µm Nickel
Lid Plating	2.0 to 3.0 µm Nickel
Body	Al ₂ O ₃ Ceramic
Pb Free	

TOP VIEW

BOTTOM VIEW



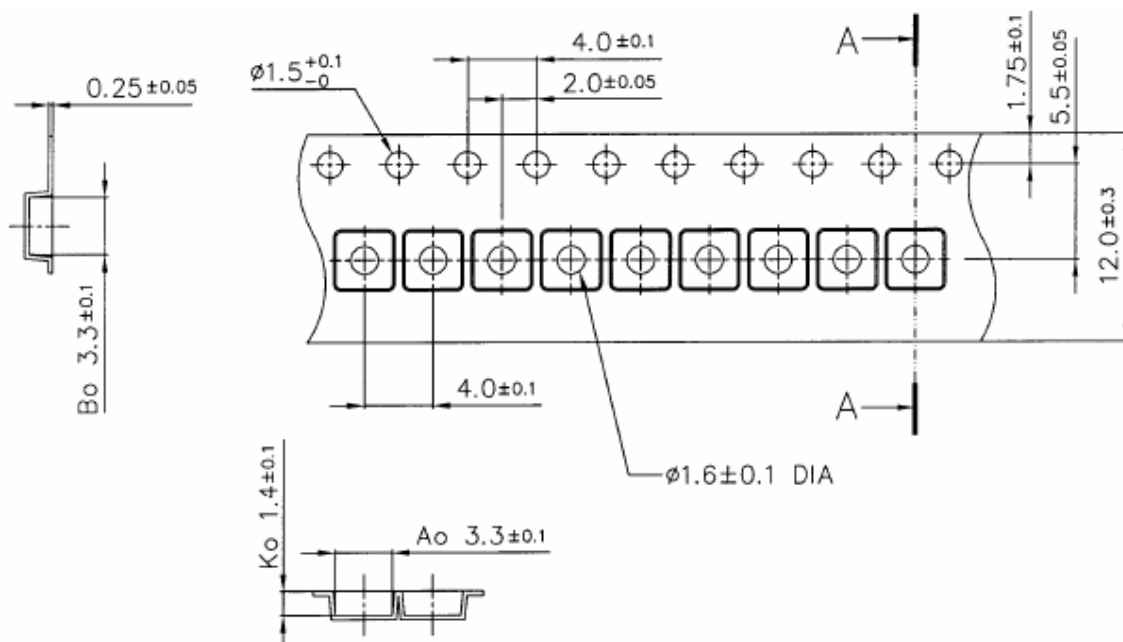
Tape and Reel Specifications



“B” Nominal Size		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000

Carrier Tape Dimensions	
Ao	3.30 mm
Bo	3.30 mm
Ko	1.4 mm
Pitch	4.0 mm
W	12.0 mm

COMPONENT ORIENTATION and DIMENSIONS



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C+0/-5°C peak (20~40sec).
4. Time: 2 times.

